

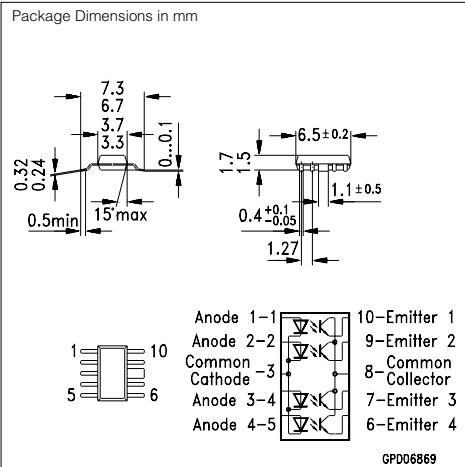
SIEMENS

NEW

SFH6941T

LOW CURRENT INPUT MINI OPTOCOUPLER

Preliminary Data Sheet



FEATURES

- Transistor Optocoupler in SOT223 Package
- End Stackable, 1.27 mm Spacing
- Low Current Input
- Very High CTR, 150% Typical at $I_F=1$ mA, $V_{CE}=0.5$ V
- Good CTR Linearity Versus Forward Current
- Minor CTR Degradation
- Field Effect Stable by TRIOS® (Transparent ION Shield)
- High Collector-Emitter Voltage, $V_{CEO}=70$ V
- Low Coupling Capacitance
- High Common Mode Transient Immunity
- Isolation Test Voltage: 2500 VDC
- Available in Tape and Reel (suffix T)

APPLICATIONS

- Telecommunication
- SMT
- PCMCIA
- Instrumentation

DESCRIPTION

The SFH6941T is a four channel mini-optocoupler suitable for high density packaged PCB application. It has a minimum of 2500 VDC isolation from input to output. The device consists of four phototransistors as detectors. Each channel is individually controlled. The optocoupler is housed in a SOT223 package. All the cathodes of the input LEDs and all the collectors of the output transistors are commoned enabling a pin count reduction from 16 pins to 10 pins—a significant space savings as compared to four channels that are electrically isolated individually.

Absolute Maximum Ratings

Emitter (GaAlAs)

Reverse Voltage	3 V
DC Forward Current.....	5 mA
Surge Forward Current ($t_p \leq 10 \mu s$)	100 mA
Total Power Dissipation.....	10 mW

Detector (Si Phototransistor)

Collector-Emitter Voltage	70 V
Emitter-Collector Voltage	7 V
Collector Current.....	10 mA
Surge Collector Current ($t_p \leq 1 ms$)	20 mA
Total Power Dissipation.....	20 mW

Package Insulation

Isolation Test Voltage (between emitter and detector, refer to climate DIN 40046, part 2, Nov. 74).....	2500 VDC
Creepage	≥ 4 mm
Clearance.....	≥ 4 mm
Comparative Tracking Index per DIN IEC 112/VDE0303, part 1	175
Isolation Resistance	
$V_{IO}=100$ V, $T_A=25^\circ C$	$\geq 10^{11} \Omega$
$V_{IO}=100$ V, $T_A=100^\circ C$	$\geq 10^{10} \Omega$
Storage Temperature Range	-55 to +150°C
Ambient Temperature Range.....	-55 to +100°C
Junction Temperature	100°C
Soldering Temperature ($t=10$ sec. max.)	260°C

Dip soldering plus reflow soldering processes

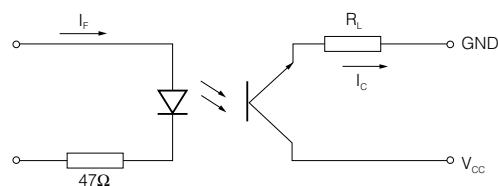
Specifications subject to change.

Characteristics ($T_A=25^\circ\text{C}$, unless otherwise specified)

Description	Symbol	Min.	Typ.	Max.	Unit
Emitter (IR GaAs)					
Forward Voltage, $I_F=5 \text{ mA}$	V_F		1.25		V
Reverse Current, $V_R=3 \text{ V}$	I_R		0.01	10	μA
Capacitance, $V_R=0 \text{ V}, f=1 \text{ MHz}$	C_0		5		pF
Thermal Resistance	R_{thJA}		1000		$^\circ\text{K/W}$
Detector (Si Phototransistor)					
Collector-Emitter Voltage, $I_{CE}=10 \mu\text{A}$	V_{CEO}	70			V
Emitter-Collector Voltage, $I_{EC}=10 \mu\text{A}$	V_{ECO}	7			V
Capacitance, $V_{CE}=5 \text{ V}, f=1 \text{ MHz}$	C_{CE}		6		pF
Thermal Resistance	R_{thJA}		500		$^\circ\text{K/W}$
Package					
Coupling Capacitance	C_C		1		pF

Description	Symbol	Values			Unit
		-3	-4	-5	
Coupling Transfer Ratio $I_F=1 \text{ mA}, V_{CE}=0.5 \text{ V}$ $I_F=0.5 \text{ mA}, V_{CE}=1.5 \text{ V}$	I_C/I_F	100–200 120 (≥ 50)	160–320 200 (≥ 80)	250–500 300 (≥ 125)	%
Collector-Emitter Saturation Voltage $I_F=1 \text{ mA}$	V_{CESat}	0.25 (≤ 0.4) ($I_C=0.5 \text{ mA}$)	0.25 (≤ 0.4) ($I_C=0.8 \text{ mA}$)	0.25 (≤ 0.4) ($I_C=1.25 \text{ mA}$)	V
Collector-Emitter Leakage Current $V_{CE}=10 \text{ V}$	I_{CEO}	50	50	50	nA

Switching times, typical



Description	Symbol	Values	Unit	Test Conditions
Turn-on Time	t_{on}	3	μs	$I_F=2 \text{ mA}$ $R_L=100 \Omega$ $T_A=25^\circ\text{C}$ $V_{CC}=5 \text{ V}$
Rise Time	t_r	2.6		
Turn-off Time	t_{off}	3.1		
Fall Time	t_f	2.8		

